

What is claimed is:

- 1 1. A method for fabricating a microelectromechanical device, comprising the steps of:
 - 2 a) providing a silicon substrate having first and second opposing surfaces;
 - 3 b) forming first and second silicon oxide layers on said first and second
 - 4 surfaces of said substrate, respectively;
 - 5 c) coating a first photoresist layer on said first silicon oxide layer;
 - 6 d) defining a first pattern on said first photoresist layer;
 - 7 e) transferring said first pattern onto said first silicon oxide layer;
 - 8 f) performing at least one additional processing step that does not perturb
 - 9 said first pattern while said silicon substrate under said first pattern
 - 10 is protected by said first silicon oxide layer; and
 - 11 g) etching, after the step of performing said at least one additional
 - 12 processing step, said first pattern into said silicon substrate.
- 1 2. The method of claim 1, wherein said at least one additional processing step comprises
 - 2 coating, defining, and transferring at least one additional pattern onto at least one
 - 3 of said first and second silicon oxide layers.
- 1 3. The method of claim 2, wherein said at least one additional processing step further
 - 2 comprises etching said at least one additional pattern into said silicon substrate.
- 1 4. A method for fabricating a microelectromechanical device, comprising the steps of:
 - 2 a) providing a silicon substrate having first and second opposing surfaces;
 - 3 b) forming first and second silicon oxide layers on said first and second
 - 4 surfaces of said substrate, respectively;
 - 5 c) coating a first photoresist layer on said first silicon oxide layer;

- 6 d) defining a first pattern on said first photoresist layer;
- 7 e) transferring said first pattern onto said first silicon oxide layer;
- 8 f) removing said first photoresist layer;
- 9 g) coating a second photoresist layer on said first silicon oxide layer;
- 10 h) defining a second pattern on said second photoresist layer, wherein said
- 11 second pattern includes said first pattern as a subset, whereby said
- 12 first pattern is not occluded by said second photoresist layer;
- 13 i) etching, after the step of defining said second pattern, said first pattern
- 14 into said silicon substrate for a first period of time;
- 15 j) transferring said second pattern onto said first silicon oxide layer; and
- 16 k) etching simultaneously, after the step of transferring said second pattern,
- 17 said first and second patterns for a second period of time.

1 5. A method for fabricating a microelectromechanical device, comprising the steps of:

- 2 a) providing a silicon substrate having first and second opposing surfaces;
- 3 b) forming first and second silicon oxide layers on said first and second
- 4 surfaces of said substrate, respectively;
- 5 c) coating a first photoresist layer on said first silicon oxide layer;
- 6 d) defining simultaneously a first pattern and a second pattern on said first
- 7 photoresist layer;
- 8 e) transferring said first pattern and said second pattern onto said first
- 9 silicon oxide layer;
- 10 f) removing said first photoresist layer;
- 11 g) coating a second photoresist layer on said first silicon oxide layer;

- h) defining simultaneously a third pattern and said first pattern on said second photoresist layer such that said second pattern remains occluded by said second photoresist layer;
- i) etching, after the step of defining said third pattern and said first pattern, said first pattern into said silicon substrate for a first period of time;
- j) transferring said third pattern onto said first silicon oxide layer;
- k) etching simultaneously, after the step of transferring said third pattern, said first and third patterns for a second period of time;
- l) removing said second photoresist layer; and
- m) etching simultaneously said first, second and third patterns for a third period of time.

6. A method for fabricating a microelectromechanical device, comprising the steps of:

- a) providing a silicon substrate having first and second opposing surfaces;
- b) doping said first surface with a dopant of a same conductivity type as a conductivity type of said substrate;
- c) forming a pad oxide on said first surface;
- d) forming a silicon nitride film on said pad oxide;
- e) patterning and etching said silicon nitride film to form at least one silicon nitride contact area on said pad oxide;
- f) performing, after step (e), at least one intervening process step, at least one of said at least one intervening process steps providing a thermal oxidation of said silicon substrate;
- g) removing, after step (f), said at least one silicon nitride contact area and any of said pad oxide beneath said at least one silicon nitride

14 contact area, thereby forming at least one contact area on said first
15 surface; and

16 h) depositing a metal on said at least one contact area.

1 7. A method for fabricating a microelectromechanical device, comprising the steps of:

2 a) providing a silicon substrate having first and second opposing surfaces;

3 b) doping said first surface with a dopant of a same conductivity type as a
4 conductivity type of said substrate;

5 c) forming a pad oxide on said first surface;

6 d) forming a silicon nitride film on said pad oxide;

7 e) patterning and etching said silicon nitride film to form at least one silicon
8 nitride contact area on said pad oxide;

9 f) forming first and second silicon oxide layers on said first and second
10 surfaces of said substrate, respectively;

11 g) coating a first photoresist layer on a first one of said first and said second
12 silicon oxide layers;

13 h) defining a first pattern on said first photoresist layer;

14 i) transferring said first pattern onto said first one of said first and said
15 second silicon oxide layers;

16 j) coating a second photoresist layer, defining, and transferring a second
17 pattern onto a second one of said first and second silicon oxide
18 layers;

19 k) removing said second photoresist layer;

- 20 l) coating a third photoresist layer and defining a third pattern onto said
 21 second one of said first and second silicon oxide layers, said third
 22 pattern including as a subset said second pattern;
- 23 m) etching, after the step of defining said third pattern, said second pattern
 24 into said silicon substrate for a first period of time;
- 25 n) transferring said third pattern onto said second one of said first and
 26 second silicon oxide layers;
- 27 o) etching simultaneously, after the step of transferring said third pattern,
 28 said second and third patterns into said silicon substrate for a second
 29 period of time;
- 30 p) removing said third photoresist layer if said third photoresist layer
 31 occludes said first pattern;
- 32 q) etching said first pattern into said silicon substrate;
- 33 r) removing, after step (q), said at least one silicon nitride contact area and
 34 any of said pad oxide beneath said at least one silicon nitride
 35 contact area, thereby forming a contact area on said first surface;
 36 and
- 37 s) depositing a metal on said contact area.

1 8. A method according to claim 7, wherein said first one of said first and second silicon
 2 oxide layers and said second one of said first and second silicon oxide layers are
 3 the same layer.

1 9. A method according to claim 7, wherein said first one of said first and second silicon
 2 oxide layers and said second one of said first and second silicon oxide layers are
 3 different layers.

1 10. A method for fabricating an integrated liquid chromatography/electrospray ionization
 2 microelectromechanical device, comprising the steps of:

- 3 a) providing a silicon substrate having an ejection surface and an opposing
4 separation surface;
- 5 b) forming first and second silicon oxide layers on said ejection and
6 separation surfaces of said substrate, respectively;
- 7 c) doping said ejection surface with a dopant of a same conductivity type as
8 a conductivity type of said substrate;
- 9 d) forming a silicon nitride film on said first silicon oxide layer;
- 10 e) patterning and etching said silicon nitride film to form at least one silicon
11 nitride contact area on said first silicon oxide layer;
- 12 f) oxidizing said substrate, after step (e), to increase said first and second
13 silicon oxide layers;
- 14 g) coating a first photoresist layer on said second silicon oxide layer;
- 15 h) defining a first pattern on said first photoresist layer, said first pattern
16 including a separation channel, a separation channel terminus, and a
17 plurality of separation posts;
- 18 i) transferring said first pattern onto said second silicon oxide layer;
- 19 j) removing said first photoresist layer;
- 20 k) coating, defining, and transferring a second pattern consisting of a fluid
21 reservoir and a first portion of a nozzle channel onto said second
22 silicon oxide layer when said first pattern does not include said fluid
23 reservoir; otherwise, coating and defining said second pattern onto
24 said separation surface when said fluid reservoir is also included in
25 said first pattern;
- 26 l) etching said second pattern into said silicon substrate;

- 27 m) coating, defining, and transferring a third pattern onto said first silicon
28 oxide layer, said third pattern consisting of an introduction channel
29 and a second portion of said nozzle channel, said third pattern being
30 aligned on said first silicon oxide layer such that said second portion
31 and said first portion of said nozzle channel are substantially axially
32 aligned, and such that said fluid reservoir and said introduction
33 channel are substantially aligned;
- 34 n) removing all photoresist provided in coating, defining, and transferring
35 said third pattern;
- 36 o) coating and defining a fourth pattern onto said first silicon oxide layer,
37 said fourth pattern consisting of an introduction channel, a second
38 portion of said nozzle channel, and a recessed area surrounding an
39 unrecessed area, wherein a nozzle is defined by said nozzle channel
40 within said unrecessed area;
- 41 p) etching, after the step of defining said fourth pattern, said third pattern
42 into said silicon substrate for a first period of time;
- 43 q) transferring said fourth pattern onto said first silicon oxide layer;
- 44 r) etching simultaneously, after the step of transferring said fourth pattern,
45 said third and fourth patterns for a second period of time;
- 46 s) removing at least all photoresist layers which occlude said first pattern;
- 47 t) etching said first pattern into said silicon substrate;
- 48 u) forming, after step (t), an isolation layer on all silicon surfaces of said
49 silicon substrate;
- 50 v) attaching, after step (u), a cover substrate to said separation surface of
51 said silicon substrate;

- 52 w) removing, after step (v), said at least one silicon nitride contact area and
53 any of said pad oxide beneath said at least one silicon nitride
54 contact area, thereby forming at least one contact area on said
55 ejection surface; and
- 56 x) depositing a metal on said at least one contact area.

1 11. A method according to claim 10, wherein said isolation layer is an electrical isolation
2 layer.

1 12. A method according to claim 10, wherein said isolation layer is a biocompatibility
2 isolation layer.

1 13. A method for fabricating a microelectromechanical device, comprising the steps of:

2 a) providing a silicon substrate having first and second opposing surfaces;

3 b) doping said first surface with a dopant of a same conductivity type as a
4 conductivity type of said substrate;

5 c) forming a pad oxide on said first surface;

6 d) forming a silicon nitride film on said pad oxide;

7 e) patterning and etching said silicon nitride film to form at least one silicon
8 nitride contact area on said pad oxide;

9 f) forming first and second silicon oxide layers on said first and second
10 surfaces of said substrate, respectively;

11 g) coating a first photoresist layer on one of said first and said second
12 silicon oxide layers;

13 h) defining a first pattern on said first photoresist layer;

14 i) transferring said first pattern onto said one of said first and said second
15 silicon oxide layers;

- 16 j) removing said first photoresist layer;
- 17 k) coating a second photoresist layer on said one of said first and said
- 18 second silicon oxide layers;
- 19 l) defining a second pattern on said second photoresist layer, wherein said
- 20 second pattern includes as a subset said first pattern, whereby said
- 21 first pattern is not occluded by said second photoresist layer;
- 22 m) etching, after the step of defining said second pattern, said first pattern
- 23 into said silicon substrate for a first period of time;
- 24 n) transferring said second pattern onto said one of said first and said
- 25 second silicon oxide layers;
- 26 o) etching simultaneously, after the step of transferring said second pattern,
- 27 said first and second patterns for a second period of time;
- 28 p) removing, after step (o), said at least one silicon nitride contact area and
- 29 any of said pad oxide beneath said at least one silicon nitride
- 30 contact area, thereby forming at least one contact area on said first
- 31 surface; and
- 32 q) depositing a metal on said at least one contact area.

1 14. A method for fabricating an electrospray ionization microelectromechanical device,
2 comprising the steps of:

- 3 a) providing a silicon substrate having an injection surface and an opposing
- 4 ejection surface;
- 5 b) forming first and second silicon oxide layers on said injection and
- 6 ejection surfaces of said substrate, respectively;
- 7 c) doping a portion of said silicon substrate through said first silicon oxide
- 8 layer with a dopant of a same conductivity type as a conductivity
- 9 type of said substrate;

- 10 d) forming a silicon nitride film on said first silicon oxide layer;
- 11 e) patterning and etching said silicon nitride film to form at least one silicon
12 nitride contact area on said first silicon oxide layer;
- 13 f) oxidizing said substrate, after step (e), to increase said first and second
14 silicon oxide layers;
- 15 g) coating a first photoresist layer on said first silicon oxide layer;
- 16 h) defining a first pattern on said first photoresist layer, said pattern
17 consisting of a nozzle channel;
- 18 i) transferring said first pattern onto said first silicon oxide layer;
- 19 j) etching said first pattern into said silicon substrate for a first period of
20 time;
- 21 k) removing said first photoresist layer;
- 22 l) coating a second photoresist layer on said second silicon oxide layer;
- 23 m) defining a second pattern on said second photoresist layer, said second
24 pattern consisting of a nozzle orifice, said second pattern being
25 aligned on said second photoresist layer such that said nozzle orifice
26 and said nozzle channel are substantially axially aligned;
- 27 n) transferring said second pattern into said second silicon oxide layer;
- 28 o) removing said second photoresist layer;
- 29 p) coating a third photoresist layer on said second silicon oxide layer;
- 30 q) defining a third pattern in said third photoresist layer, said third pattern
31 consisting of a recessed region and a portion corresponding to said
32 nozzle orifice, wherein said second pattern is not occluded by said
33 third photoresist layer;

- 34 r) etching, after the step of defining said third pattern, said second pattern
- 35 into said silicon substrate for a second period of time;
- 36 s) transferring said third pattern into said second silicon oxide layer;
- 37 t) etching simultaneously, after the step of transferring said third pattern,
- 38 said second and third patterns into said silicon substrate for a third
- 39 period of time;
- 40 u) forming, after step (t), an isolation layer on at least all silicon surfaces of
- 41 said nozzle channel;
- 42 v) removing, after step (u), said at least one silicon nitride contact area and
- 43 any of said first silicon oxide layer beneath said at least one silicon
- 44 nitride contact area, thereby forming at least one contact area on
- 45 said first surface; and
- 46 w) depositing a metal on said at least one contact area.

1 15. A method according to claim 14, wherein said isolation layer is an electrical isolation
2 layer.

1 16. A method according to claim 14, wherein said isolation layer is a biocompatibility
2 isolation layer.

1 17. A method for fabricating a microelectromechanical device, comprising the steps of:

- 2 a) providing a silicon substrate having first and second opposing surfaces;
- 3 b) doping said first surface with a dopant of a same conductivity type as a
- 4 conductivity type of said substrate;
- 5 c) forming a pad oxide on said first surface;
- 6 d) forming a silicon nitride film on said pad oxide;
- 7 e) patterning and etching said silicon nitride film to form at least one silicon
- 8 nitride contact area on said pad oxide;

- 9 f) forming first and second silicon oxide layers on said first and second
10 surfaces of said substrate, respectively;
- 11 g) coating a first photoresist layer on one of said first and said second
12 silicon oxide layers;
- 13 h) defining a first pattern on said first photoresist layer;
- 14 i) transferring said first pattern onto said one of said first and said second
15 silicon oxide layers;
- 16 j) performing at least one additional processing step that does not perturb
17 said first pattern while said silicon substrate under said first pattern
18 is protected by said first silicon oxide layer;
- 19 k) etching, after the step of performing said at least one additional
20 processing step, said first pattern into said silicon substrate;
- 21 l) removing, after step (k), said at least one silicon nitride contact area and
22 any of said pad oxide beneath said at least one silicon nitride
23 contact area, thereby forming at least one contact area on said first
24 surface; and
- 25 m) depositing a metal on said at least one contact area.

1 18. The method of claim 17, wherein said at least one additional processing step comprises
2 coating, defining, and transferring at least one additional pattern onto at least one
3 of said first and second silicon oxide layers.

1 19. The method of claim 18, wherein said at least one additional processing step further
2 comprises etching said at least one additional pattern into said silicon substrate.

1 20. A method for fabricating a liquid chromatography microelectromechanical device,
2 comprising the steps of:

- a) providing a silicon substrate having an introduction surface on an introduction side of said substrate and an opposing separation surface on a separation side of said substrate;
- b) forming first and second silicon oxide layers on said introduction and separation surfaces of said substrate, respectively;
- c) doping a portion of said introduction surface through said first silicon oxide layer with a dopant of a same conductivity type as a conductivity type of said substrate;
- d) forming a silicon nitride film on said first silicon oxide layer;
- e) patterning and etching said silicon nitride film to form at least one silicon nitride contact area on said first silicon oxide layer;
- f) oxidizing said substrate, after step (e), to increase said first and second silicon oxide layers;
- g) coating a first photoresist layer on said introduction side;
- h) defining a first pattern on said first photoresist layer, said first pattern consisting of an introduction channel and an introduction-side exit channel;
- i) transferring said first pattern onto said first silicon oxide layer;
- j) etching said first pattern into said silicon substrate;
- k) removing said first photoresist layer;
- l) coating a second photoresist layer on said separation side;
- m) defining and transferring a second pattern onto said second silicon oxide layer, said second pattern including a separation channel, a separation channel terminus, and a plurality of separation posts;
- n) removing said second photoresist layer;

- 28 o) coating a third photoresist layer on said separation side;
- 29 p) defining and transferring a third pattern consisting of a fluid reservoir
30 and a separation-side exit channel onto said second silicon oxide
31 layer when said second pattern does not include said fluid reservoir,
32 such that said reservoir is substantially aligned with said
33 introduction channel and said separation-side exit channel is
34 substantially aligned with said introduction-side exit channel;
35 otherwise, defining said third pattern onto said separation surface
36 when said fluid reservoir is also included in said second pattern,
37 such that said reservoir is substantially aligned with said
38 introduction channel and said separation-side exit channel is
39 substantially aligned with said introduction-side exit channel;
- 40 q) etching said third pattern into said silicon substrate so that said reservoir
41 connects with said introduction channel and said separation-side
42 exit channel connects with said introduction-side exit channel;
- 43 r) removing said third photoresist layer;
- 44 s) etching said second pattern into said silicon substrate;
- 45 t) forming, after step (s), an isolation layer on all silicon surfaces of said
46 silicon substrate;
- 47 u) attaching, after step (t), a cover substrate to said separation surface of
48 said silicon substrate;
- 49 v) removing, after step (u), said at least one silicon nitride contact area and
50 any of said first silicon oxide layer beneath said at least one silicon
51 nitride contact area, thereby forming at least one contact area on
52 said first surface; and
- 53 w) depositing a metal on said at least one contact area.

1 21. A method according to claim 20, wherein said isolation layer is an electrical isolation
2 layer.

1 22. A method according to claim 20, wherein said isolation layer is a biocompatibility
2 isolation layer.

1 23. A method for fabricating a microelectromechanical device, comprising the steps of:

2 a) providing a silicon substrate having first and second opposing surfaces;

3 b) forming first and second silicon oxide layers on said first and second
4 surfaces of said substrate, respectively;

5 c) coating a first photoresist layer on said first silicon oxide layer;

6 d) defining a first pattern on said first photoresist layer;

7 e) transferring said first pattern onto said first silicon oxide layer;

8 f) coating, defining, and transferring a second pattern onto one of said first
9 and second silicon oxide layers;

10 g) removing all photoresist provided in coating, defining, and transferring
11 said second pattern;

12 h) coating and defining a third pattern onto said one of said first and second
13 silicon oxide layers, wherein said third pattern includes as a subset
14 said second pattern, whereby said second pattern is not occluded;

15 i) etching, after the step of defining said third pattern, said second pattern
16 into said silicon substrate for a first period of time;

17 j) transferring said third pattern onto said one of said first and second
18 silicon oxide layers;

19 k) etching simultaneously, after the step of transferring said second pattern,
20 said second and third patterns for a second period of time;

21 l) removing at least all photoresist layers which occlude said first pattern;
22 and
23 m) etching said first pattern into said silicon substrate.